

MMBT3904ZK

Rev.D Mar.-2025

描述 / Descriptions

DFN1006-3L 塑封封装 NPN 半导体三极管。
Silicon NPN transistor in a DFN1006-3L Plastic Package.

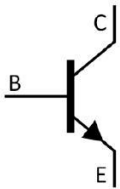
特征 / Features

低电压, 低电流, 无卤产品。
Low current, Low voltage, HF Product.

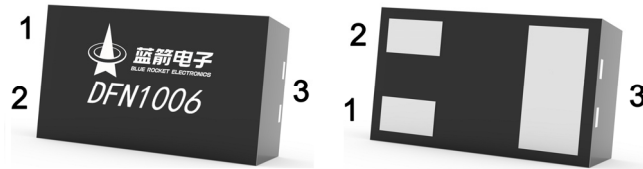
用途 / Applications

用于普通放大及开关。
General purpose amplifier and switching.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : Base PIN 2 : Emitter PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

h _{FE} Range	100~300
Marking	• H1AK

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V _{CB0}	60	V
Collector to Emitter Voltage	V _{CEO}	40	V
Emitter to Base Voltage	V _{EBO}	6.0	V
Collector Current	I _C	200	mA
*Collector Power Dissipation	P _C	100	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	-55~150	°C
Thermal Resistance, Junction to Ambient	R _{thJA}	310	°C/W
Thermal Resistance, Junction to Lead	R _{thJL}	120	°C/W

*贴装在 PCB 板上 Mount on the PCBA

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V _{CB0}	I _C =10μA I _E =0	60			V
Collector to Emitter Breakdown Voltage	V _{CEO}	I _C =1.0mA I _B =0	40			V
Emitter to Base Breakdown Voltage	V _{EBO}	I _E =10μA I _C =0	6.0			V
Collector Cut-Off Current	I _{CB0}	V _{CB} =30V I _E =0			0.05	μA
Emitter Cut-Off Current	I _{EBO}	V _{EB} =3.0V I _C =0			0.05	μA
DC Current Gain	h _{FE(1)}	V _{CE} =1.0V I _C =10mA	100		300	
	h _{FE(2)}	V _{CE} =1.0V I _C =100mA	30			
	h _{FE(3)}	V _{CE} =1.0V I _C =50mA	60			
	h _{FE(4)}	V _{CE} =1.0V I _C =1.0mA	70			
	h _{FE(5)}	V _{CE} =1.0V I _C =0.1mA	40			
Collector-Emitter Saturation Voltage	V _{CE(sat)(1)}	I _C =10mA I _B =1.0mA			0.2	V
	V _{CE(sat)(2)}	I _C =50mA I _B =5.0mA			0.3	V
Base-Emitter Saturation Voltage	V _{BE(sat)(1)}	I _C =10mA I _B =1.0mA	0.65		0.85	V
	V _{BE(sat)(2)}	I _C =50mA I _B =5.0mA			0.95	V
Transition Frequency	f _T	V _{CE} =20V I _C =10mA f=100MHz	300			MHz
Output Capacitance	C _{ob}	V _{CB} =5.0V f=1.0MHz			4.0	pF
Storage Time	t _{stg}	V _{CC} =3.0V I _C =10mA I _{B1} =-I _{B2} =1.0mA			200	ns
Fall Time	t _f	V _{CC} =3.0V I _C =10mA I _{B1} =-I _{B2} =1.0mA			50	ns
Delay Time	t _d	V _{CC} =3.0V V _{BE} =0.5V I _C =10mA I _{B1} =1.0mA			35	ns
Rise Time	t _r	V _{CC} =3.0V V _{BE} =0.5V I _C =10mA I _{B1} =1.0mA			35	ns
Input Capacitance	C _{ib}	V _{EB} =0.5V f=1.0MHz			8.0	pF

电参数曲线图 / Electrical Characteristic Curve

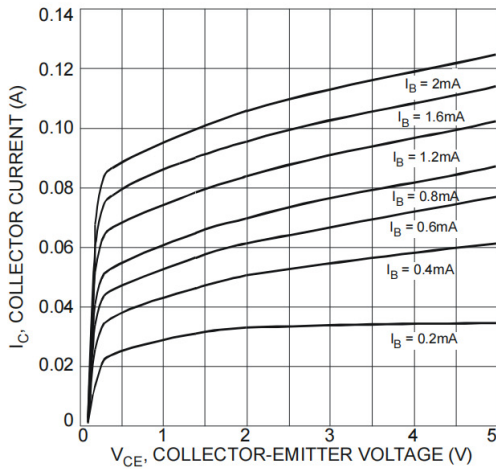


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

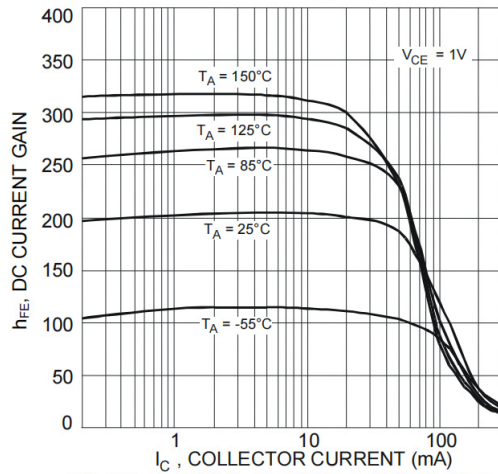


Fig. 2 Typical DC Current Gain vs. Collector Current

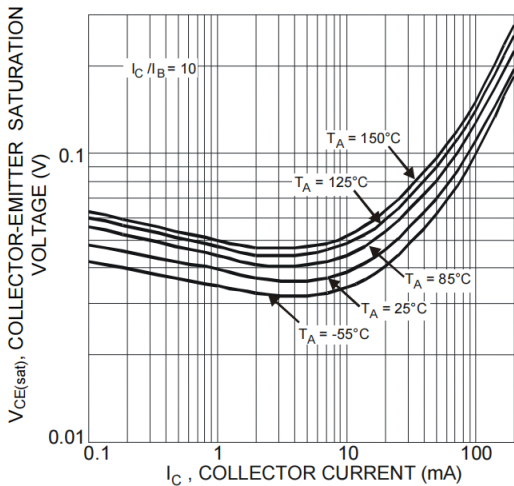


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

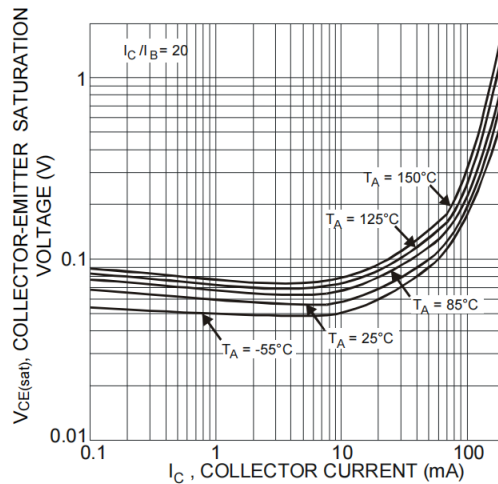


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

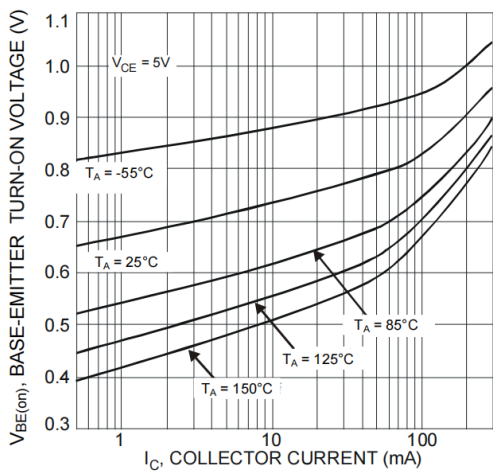


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

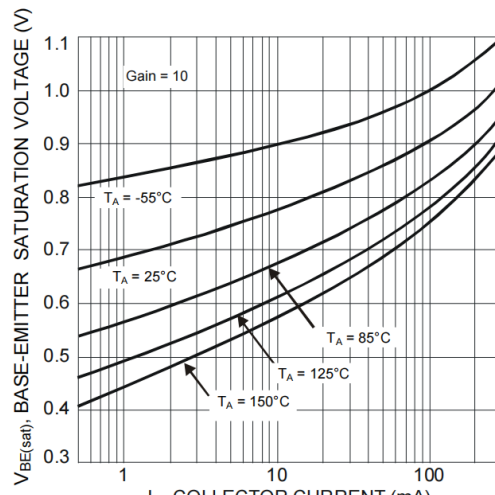
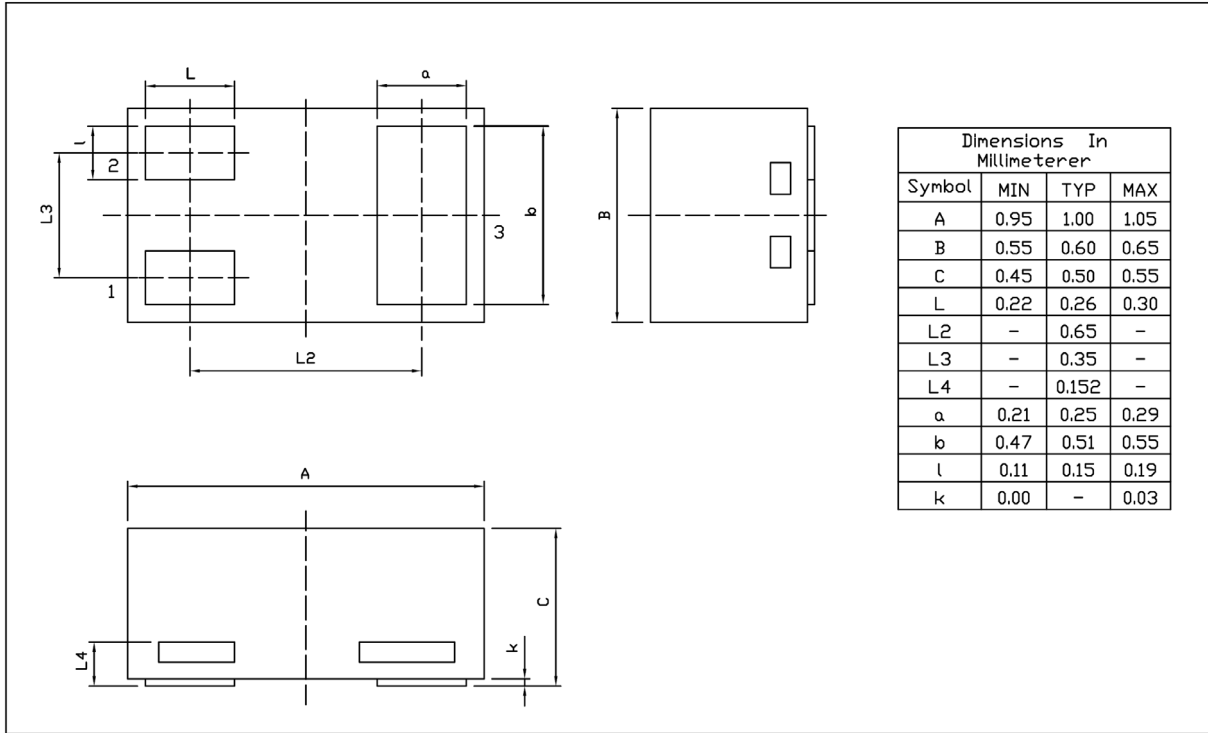


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

外形尺寸图 / Package Dimensions

DFN1006-3L

Unit:mm



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印章说明 / Marking Instructions

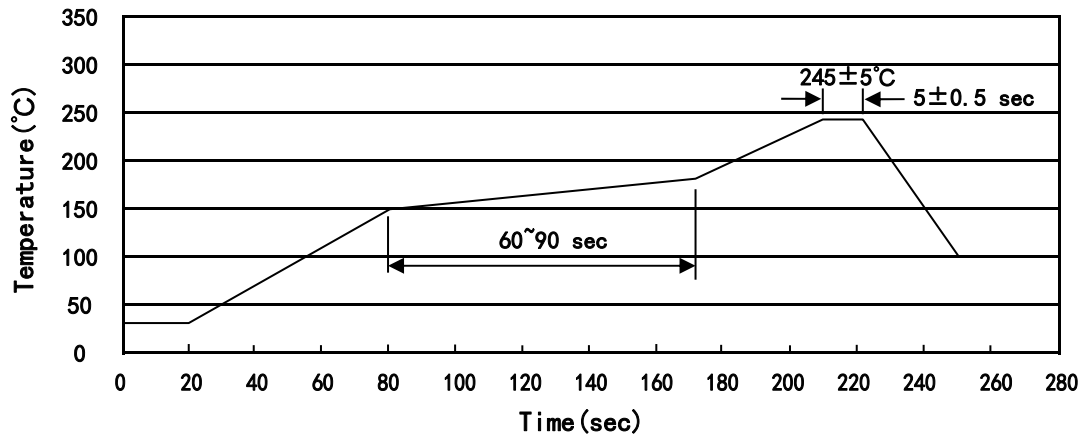


说明：

- ： 区分标识
- H： 为公司代码
- 1AK： 为型号代码

Note:

- ： Identify
- H： Company Code
- 1AK： Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
DFN1006-3L	10,000	10	100,000	6	600,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices